



THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:

C. Huang

U.S. SERIAL NO.:

10/787,269

GROUP:

2814

FILED:

February 25, 2004

EXAMINER: P. Cao

FOR:

SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING

STRUCTURE

CERTIFICATE OF EXPRESS MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on this date <u>August 18, 2006</u> in an envelope as "Express Mail Post Office to Addressee," mailing Label Number <u>EV755072377US</u> addressed to the: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

By: Kathleen M. Drury

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicant is in receipt of the Office Action dated February 21, 2006 of the above-referenced application. A Request for Continued Examination (RCE) and a three-month extension of time are submitted herewith. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.